AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1-8. (canceled).

9. (previously presented): A multilayered printed circuit board comprising:

a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and a solder resist layer formed as an outermost layer,

wherein said solder resist layer contains an elastomer component in a composition comprising a resin for said solder resist layer, and

said elastomer component is separated in micro-phase as to form an island-in-sea structure after curing in said solder resist layer.

10-30. (canceled).

31. (currently amended): A multilayered printed circuit board comprising:

a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and a solder resist layer formed as an outermost layer,

wherein said solder resist layer contains a P atom-containing epoxy resin, and

said P atom-containing epoxy resin has bivalent phosphoric acid residue with a hydroxyl group, and has epoxy groups in both terminals of the P atom-containing epoxy resin.

32. (currently amended): ~~The multilayered printed circuit board according to claim 31,~~

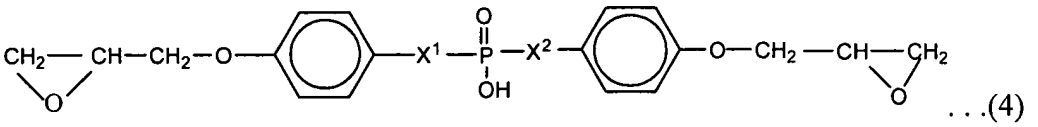
A multilayered printed circuit board comprising:

a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and a solder resist layer formed as an outermost layer,

wherein said solder resist layer contains a P atom-containing epoxy resin,

said P atom-containing epoxy resin has bivalent phosphoric acid residue, and has epoxy groups in both terminals of the P atom-containing epoxy resin, and

~~wherein~~ said epoxy resin ~~having bivalent phosphoric acid residue and having epoxy groups in both terminals is an epoxy resin having~~has the following general formula ~~[4]~~ (4)



. . .(4)

~~(~~wherein X^1~~,~~ and [[,]] X^2 respectively represent O or a single bond~~)~~.

33. (currently amended): A multilayered printed circuit board comprising: a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and a solder resist layer formed as an outermost layer,

wherein said solder resist layer contains a P atom-containing epoxy resin, and

said P atom-containing epoxy resin is an epoxy resin having a monovalent phosphoric acid residue with two hydroxyl groups in one terminal of the P atom-containing epoxy resin and an epoxy group in the other terminal of the P atom-containing epoxy resin.

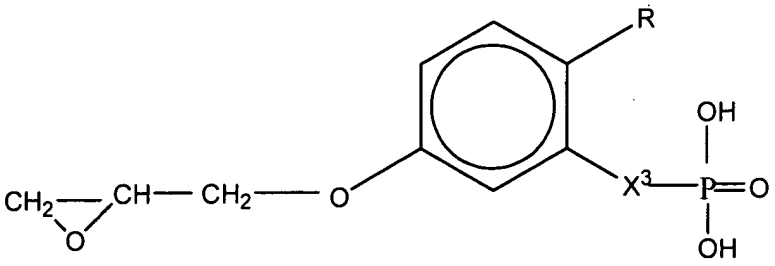
34. (currently amended): ~~The multilayered printed circuit board according to claim 33,~~ A multilayered printed circuit board comprising:

a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and a solder resist layer formed as an outermost layer,

wherein said solder resist layer contains a P atom-containing epoxy resin,

said P atom-containing epoxy resin is an epoxy resin having a monovalent phosphoric acid residue in one terminal of the P atom-containing epoxy resin and an epoxy group in the other terminal of the P atom-containing epoxy resin, and

~~wherein~~ said epoxy resin ~~having a monovalent phosphoric acid residue in one terminal and an epoxy group in the other terminal is an epoxy resin having~~has the following general formula ~~[5]~~ (5):



. . . (5)

~~(~~wherein X^3 represents O or a single bond; and R represents an alkyl of 2 to 8 carbons~~)~~.

35. (canceled).

36. (previously presented): A multilayered printed circuit board comprising:

a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and a solder resist layer formed as an outermost layer,

wherein said solder resist layer contains an elastomer component in a composition comprising a resin for said solder resist layer,

said elastomer component is at least one member selected from the group consisting of natural rubber, synthetic rubber, a thermoplastic resin and a thermosetting resin, and

said elastomer component is separated in micro-phase as to form an island-in-sea structure after curing in said solder resist layer.

37. (previously presented): The multilayered printed circuit board according to claim 31,

wherein said solder resist layer contains at least one member selected from the group consisting of a silicon compound, an aluminum compound and a magnesium compound.

38. (previously presented): The multilayered printed circuit board according to claim 33,

wherein said solder resist layer contains at least one member selected from the group consisting of a silicon compound, an aluminum compound and a magnesium compound.

39. (new): The multilayered printed circuit board according to claim 32,

wherein said solder resist layer contains at least one member selected from the group consisting of a silicon compound, an aluminum compound and a magnesium compound.

40. (new): The multilayered printed circuit board according to claim 34,

wherein said solder resist layer contains at least one member selected from the group consisting of a silicon compound, an aluminum compound and a magnesium compound.